

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

| Symbol | Parameter | | Value | Unit |
|-----------|--|---------------------------------------|---------------|--------------------|
| V_{PP} | Peak pulse voltage | IEC 61000-4-2 contact discharge | 30 | kV |
| | | IEC 61000-4-2 air discharge | 30 | |
| | | ISO10605 contact discharge | 30 | |
| | | ISO10605 air discharge | 30 | |
| | | MIL STD 883G - Method 3015-7: class 3 | 25 | |
| P_{PP} | Peak pulse power dissipation (8/20 μs) | T_j initial = T_{amb} | 150 | W |
| I_{PP} | Peak pulse current (8/20 μs) | | 9 | A |
| T_{OP} | Operating junction temperature range | | - 50 to + 125 | $^{\circ}\text{C}$ |
| T_{stg} | Storage temperature range | | - 65 to + 125 | $^{\circ}\text{C}$ |
| T_L | Maximum lead temperature for soldering during 10 s | | 260 | $^{\circ}\text{C}$ |

Figure 2. Electrical characteristics (definitions)

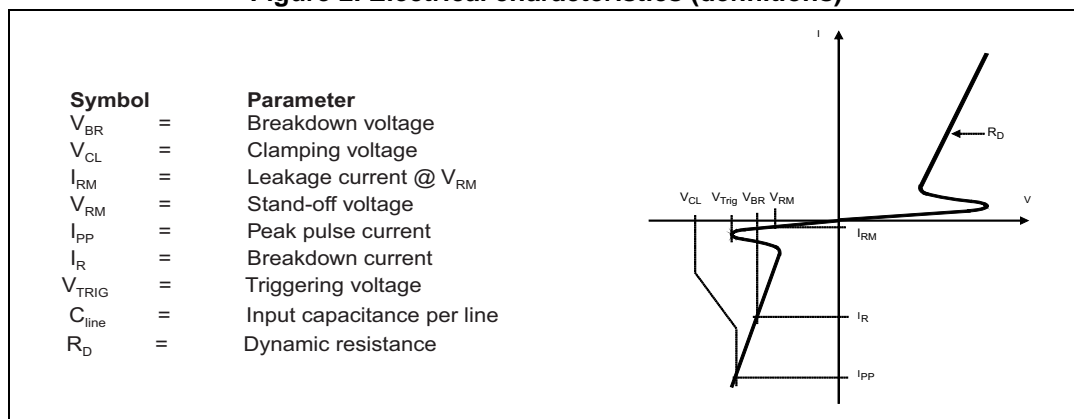


Table 2. Electrical characteristics (values, $T_{amb} = 25\text{ }^{\circ}\text{C}$)

| Symbol | Test condition | Min. | Typ. | Max. | Unit |
|------------|--|------|------|------|----------|
| V_{BR} | From I/O1 to I/O2, $I_R = 1\text{ mA}$ | 11 | 13 | 17 | V |
| | From I/O2 to I/O1, $I_R = 1\text{ mA}$ | 5.8 | 8 | 11 | |
| I_{RM} | $V_{RM} = 5\text{ V}$ | | | 60 | nA |
| R_d | Dynamic resistance, pulse width 100 ns | | | | Ω |
| | From I/O1 to I/O2 | | 0.25 | | |
| | From I/O2 to I/O1 | | 0.23 | | |
| V_{CL} | 8 kV contact discharge after 30 ns IEC 61000 4-2 | | | | V |
| | From I/O1 to I/O2 | | 17.5 | | |
| | From I/O2 to I/O1 | | 12.5 | | |
| C_{line} | $F = 1\text{ MHz}$, $V_R = 0\text{ V}$ | | 26 | 30 | pF |

Figure 3. Peak pulse power versus initial junction temperature (maximum values)

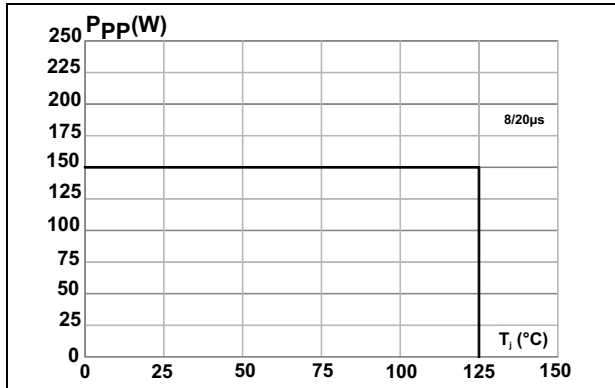


Figure 4. Junction capacitance versus reverse voltage applied (typical values)

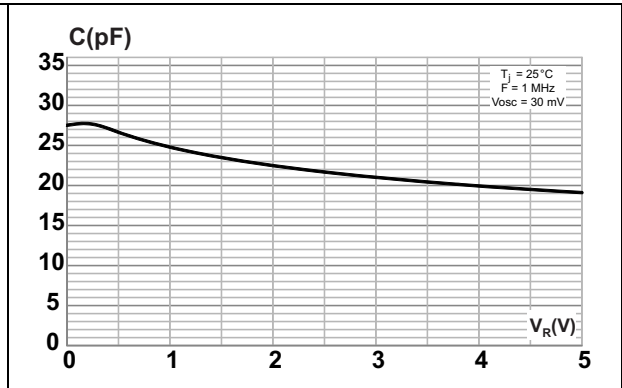


Figure 5. Peak pulse power versus exponential pulse duration (maximum values)

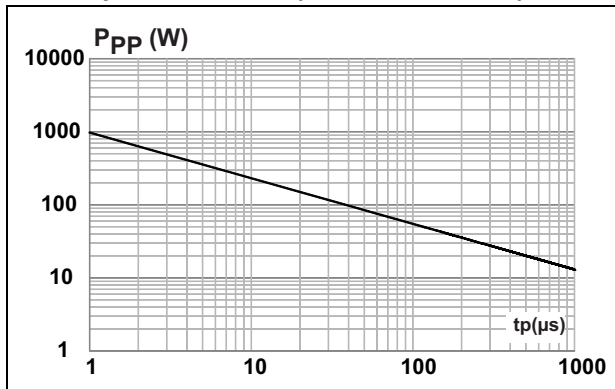


Figure 6. Clamping voltage versus peak pulse current (typical values)

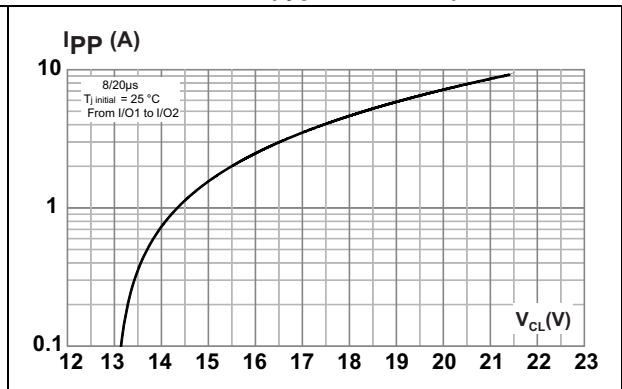


Figure 7. Clamping voltage versus peak pulse current (typical values)

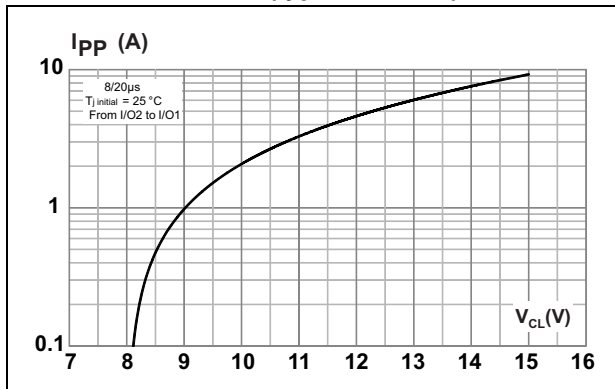


Figure 8. Leakage current versus junction temperature (typical values)

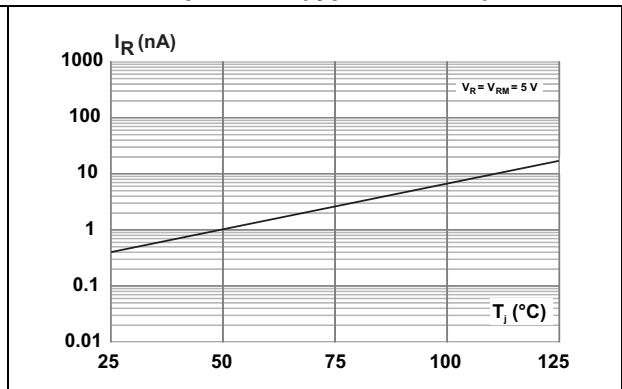


Figure 9. S21 attenuation measurement

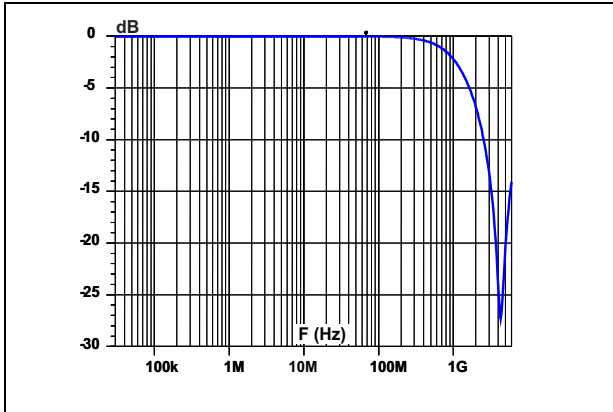


Figure 10. TLP measurements

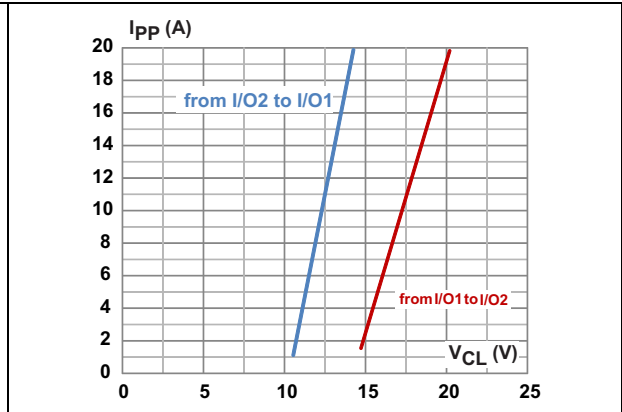


Figure 11. ESD response to ISO 10605, C = 150 pF, R = 330 Ω (+8 kV contact)

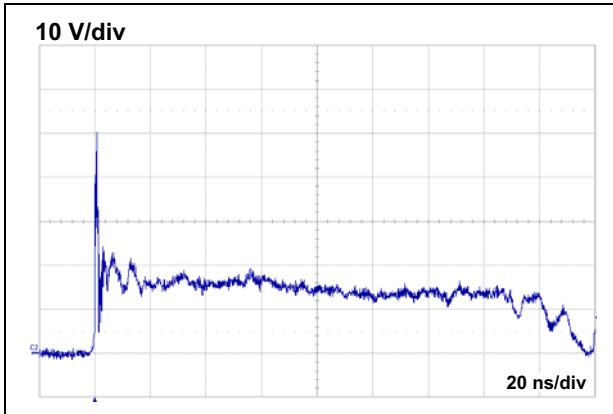


Figure 12. ESD response to ISO 10605, C = 150 pF, R = 330 Ω (-8 kV contact)

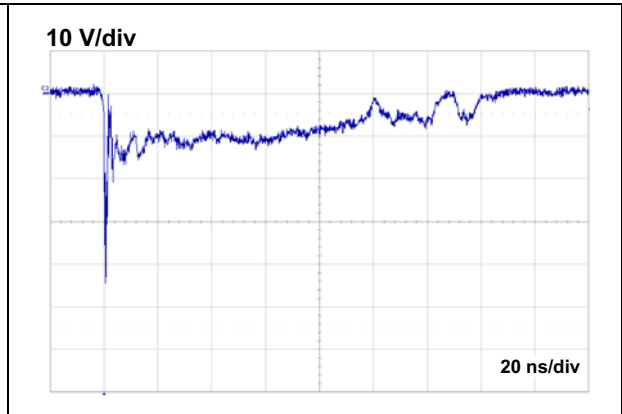


Figure 13. Response to ISO 7637-3 (pulse 3a) U_S = -150 V

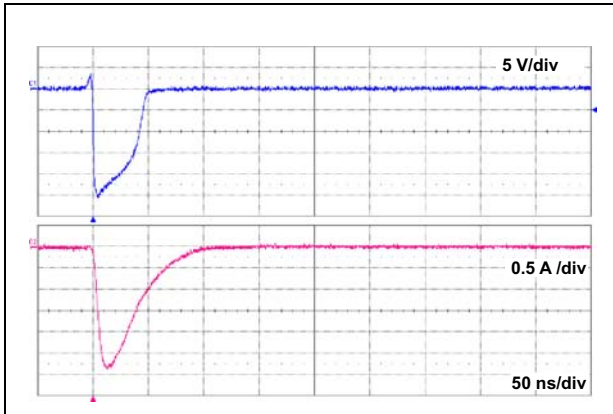
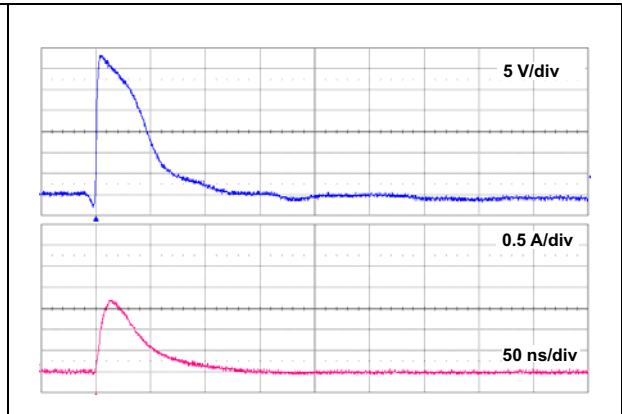


Figure 14. Response to ISO 7637-3 (pulse 3b) U_S = +100 V



2 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 15. SOD882T dimension definitions

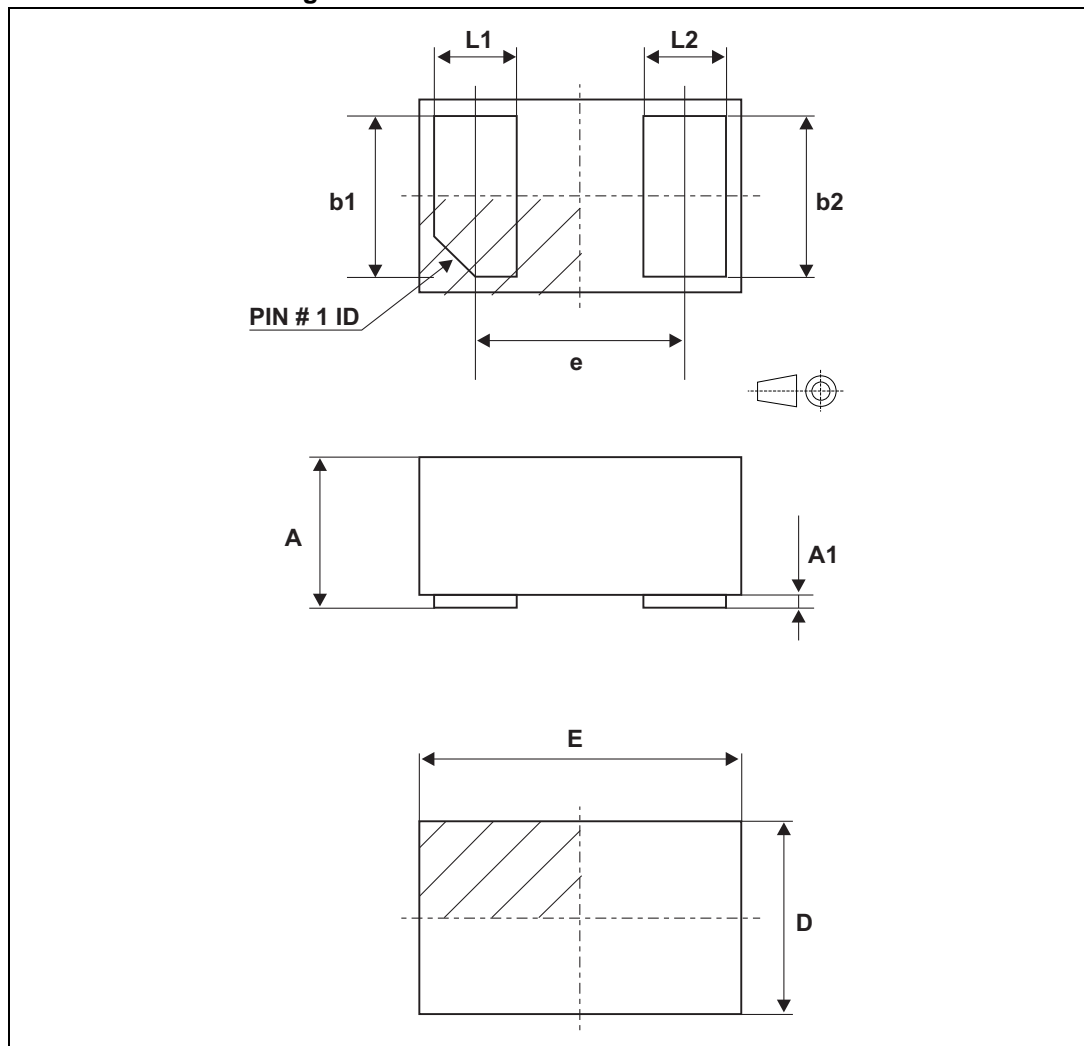


Table 3. SOD882T dimension values

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 0.30 | | 0.40 | 0.012 | | 0.016 |
| A1 | 0.00 | | 0.05 | 0.000 | | 0.002 |
| b1 | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| b2 | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| D | 0.55 | 0.60 | 0.65 | 0.022 | 0.024 | 0.026 |
| E | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| e | 0.60 | 0.65 | 0.70 | 0.024 | 0.026 | 0.028 |
| L1 | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |
| L2 | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |

Figure 16. SOD882T footprint in mm (inches)

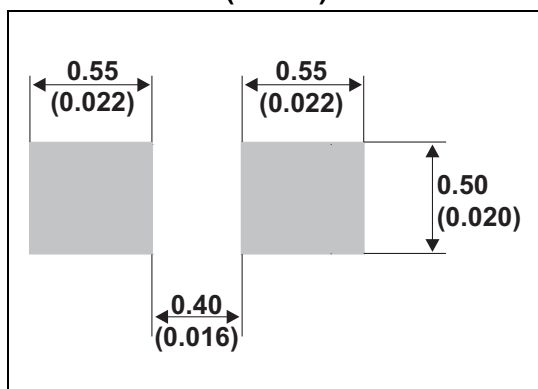
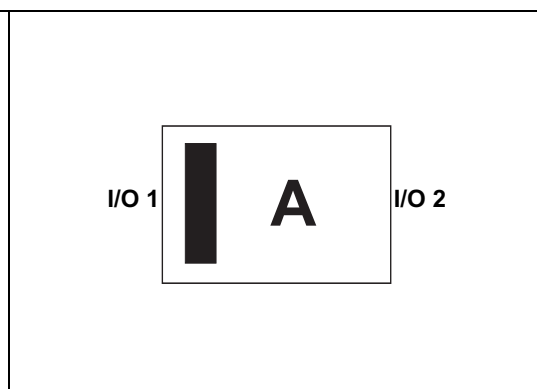
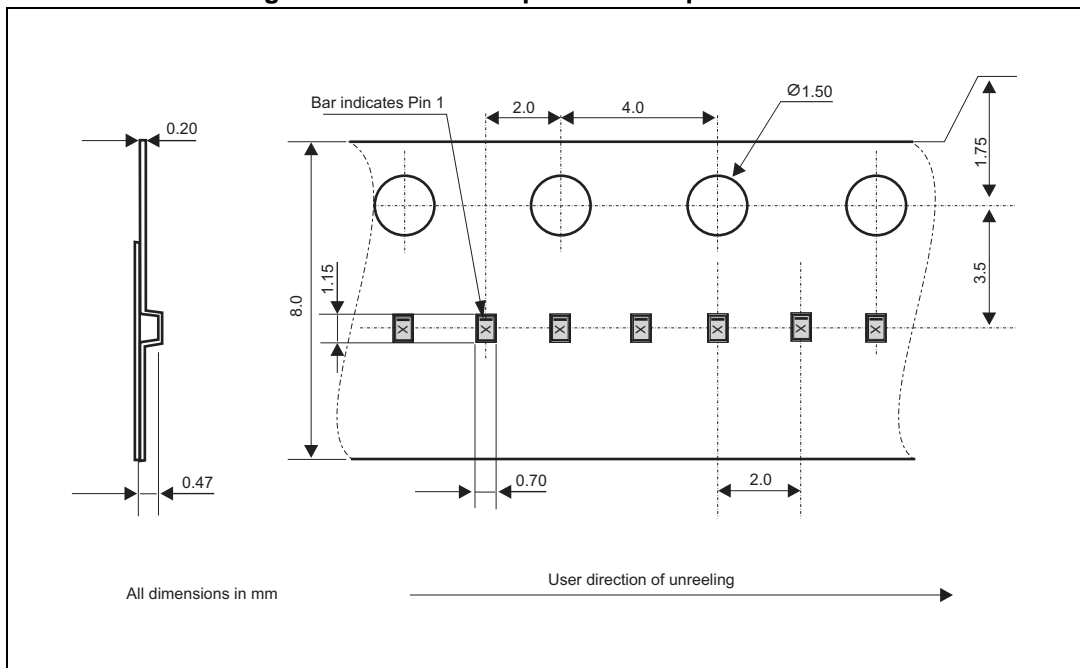


Figure 17. SOD882T marking



Note: Product marking may be rotated by multiples of 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Figure 18. SOD882T tape and reel specifications

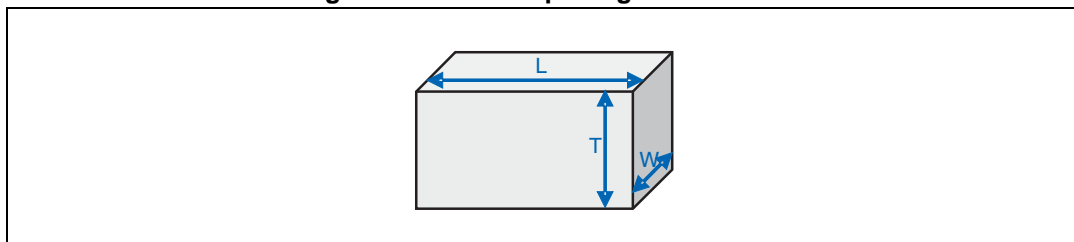


3 Recommendation on PCB assembly

3.1 Stencil opening design

1. General recommendation on stencil opening design
 - a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

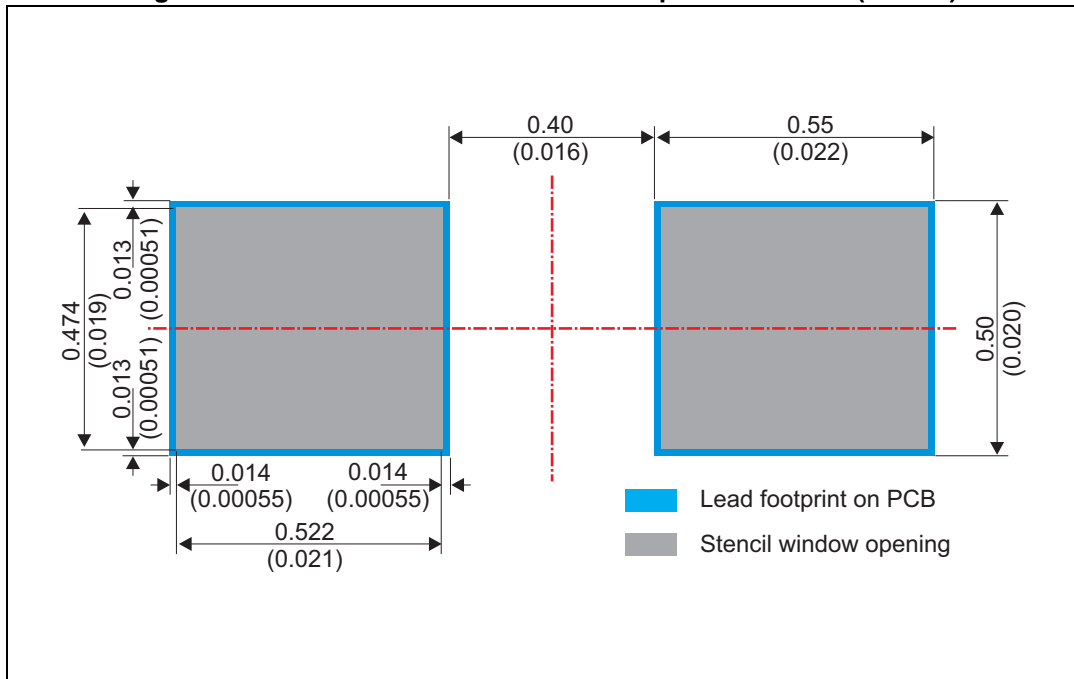
Figure 19. Stencil opening dimensions



- b) General design rule
 - Stencil thickness (T) = 75 ~ 125 μm
 - Aspect Ratio = $\frac{W}{T} \geq 1,5$
 - Aspect Area = $\frac{L \times W}{2T(L + W)} \geq 0,66$

2. Reference design
 - a) Stencil opening thickness: 100 μm
 - b) Stencil opening for central exposed pad: Opening to footprint ratio is 50%.
 - c) Stencil opening for leads: Opening to footprint ratio is 90%.

Figure 20. Recommended stencil window position in mm (inches)



3.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. “No clean” solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed.
4. Solder paste with fine particles: powder particle size is 20-45 μm .

3.3 Placement

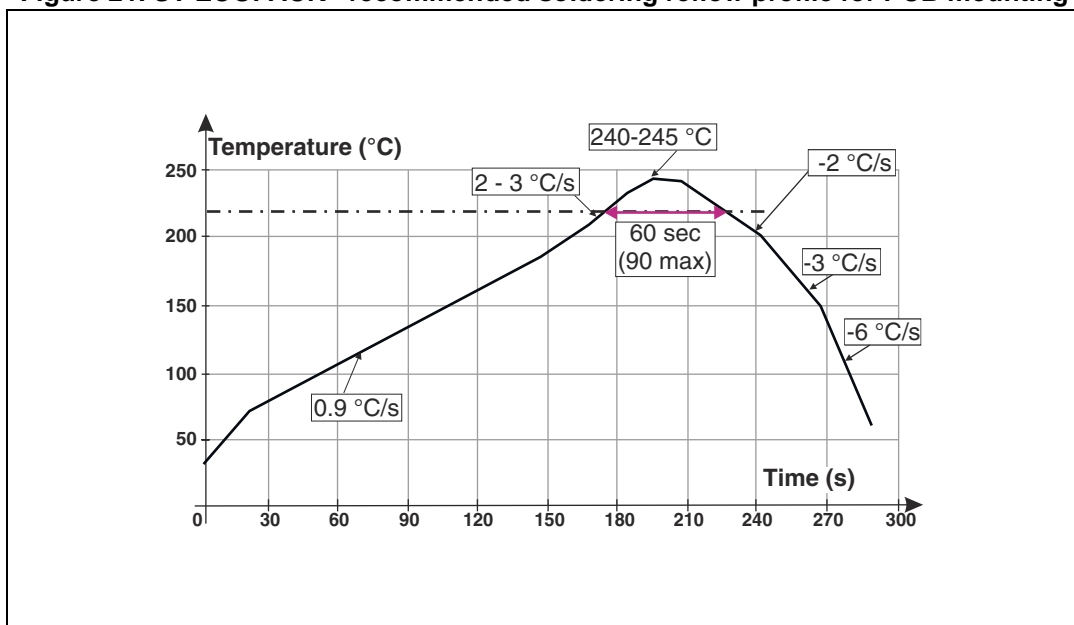
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering.
3. Standard tolerance of ± 0.05 mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

3.5 Reflow profile

Figure 21. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.

4 Ordering information

Figure 22. Ordering information scheme

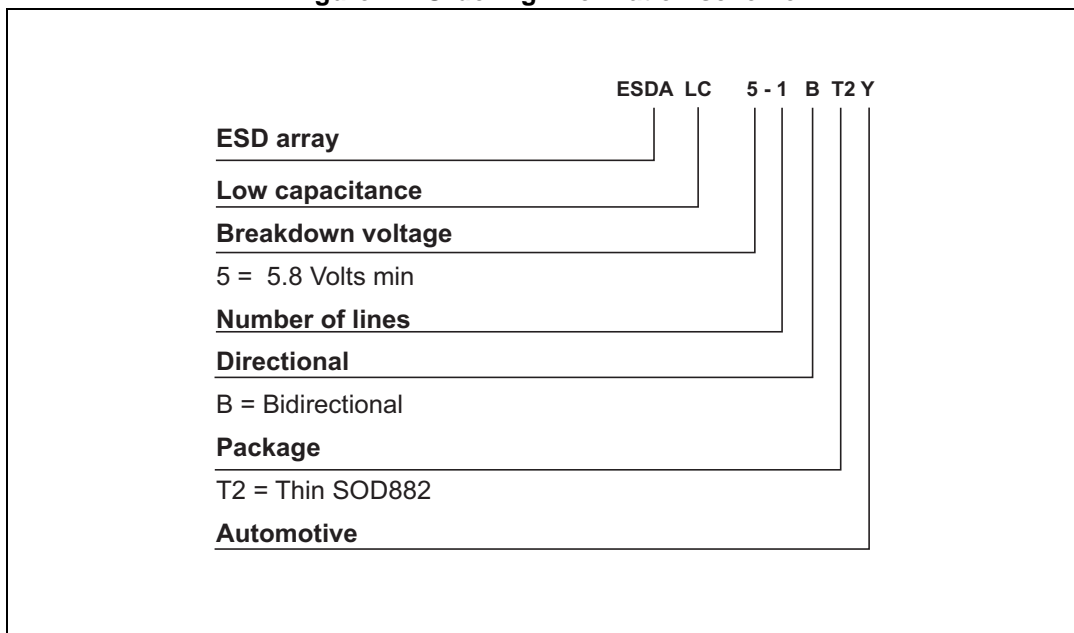


Table 4. Ordering information

| Order code | Marking ⁽¹⁾ | Package | Weight | Base qty | Delivery mode |
|---------------|------------------------|---------|---------|----------|---------------|
| ESDALC5-1BT2Y | A | SOD882T | 0.80 mg | 12000 | Tape and reel |

1. The marking can be rotated by multiples of 90° to differentiate assembly location

5 Revision history

Table 5. Document revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 03-Feb-2014 | 1 | Initial release. |

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